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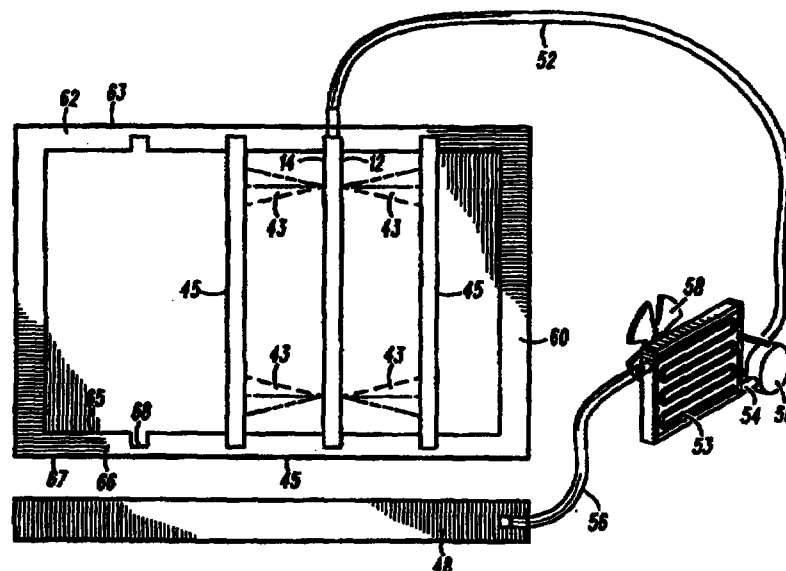
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(21) International Application Number: PCT/US97/01191 ✓ (22) International Filing Date: 24 January 1997 (24.01.97) ✓ (30) Priority Data: 08/630,135 10 April 1996 (10.04.96) ✓ US (71) Applicant: MOTOROLA INC. [US/US]; 1303 East Algonquin Road, Schaumburg, IL 60196 (US). ✓ (72) Inventors: MCDUNN, Kevin, J.; 451 Harvest Gate, Lake in the Hills, IL 60102 (US). LEMPER-BRENNER, Linda; 1927 Henley Street, Glenview, IL 60025 (US). PRESS, Minoo, D.; 402 Oakmont Lane, Schaumburg, IL 60173 (US). (74) Agents: CREPS, Heather, L. et al.; Motorola Inc., Intellectual Property Dept., 1303 East Algonquin Road, Schaumburg, IL 60196 (US).		(81) Designated States: AU, BR, CN, IL, JP, KR, MX, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i>

(54) Title: APPARATUS AND METHOD FOR SPRAY-COOLING AN ELECTRONIC MODULE**(57) Abstract**

The apparatus includes a plate (10) having a first layer (12) and a second layer (14) opposed to the first layer (12). A first fluid distributing conduit (28) is disposed in the first layer (12) and a second fluid distributing conduit (28) is disposed in the second layer (14). A first nozzle housing (30) having a first aperture (36) is disposed in the first fluid distributing conduit (28) and a second nozzle housing (30) having a second aperture (36) is disposed in the second fluid distributing conduit (28).